Semiconductor Materials Business Briefing

December 10, 2025
FUJIFILM Holdings Corporation

Business performance forecast and future predictions contained in this material are based on currently-available information and reflect potential risks and uncertainty factors.
For this reason, actual business performance could be different from such predictions due to various factors

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Value from Innovation

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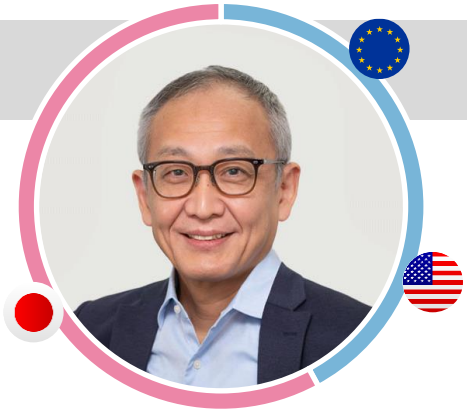
Agenda

1. Overview of the semiconductor market
2. Business strategy: One-Stop Solutions
3. R&D capacity for supporting One-Stop Solutions
4. Individual materials strategy and its progress toward achieving VISION2030
5. Conclusion

Profile



Tetsuya Iwasaki

Current positions (June,2025－)
General Manager, Electronic Materials Business Division
Director & Corporate Senior Vice President,
FUJIFILM Corporation
Representative Director and Chairman,
FUJIFILM Electronic Materials Co., Ltd.

Career Timeline

April	1986	Joined Fuji Photo Film Co., Ltd.
August	2014	General Manager, Corporate Planning Division, FUJIFILM Electronic Materials Co., Ltd
September	2016	President & Managing Director, FUJIFILM Electronics Materials (Europe) N.V [Residing in Belgium]
June	2017	General Manager, Photo Imaging Products Division, FUJIFILM Corporation
June	2019	President & CEO, FUJIFILM Holdings America Corporation President & CEO, FUJIFILM North America Corporation [Residing in U.S.A]
December	2020	Corporate Vice President, FUJIFILM Corporation President & CEO, FUJIFILM Holdings America Corporation President & CEO, FUJIFILM North America Corporation [Residing in U.S.A]
October	2021	General Manager, Electronic Materials Business Division Corporate Vice President, FUJIFILM Corporation
June	2023	General Manager, Electronic Materials Business Division Director and Corporate Vice President, FUJIFILM Corporation
June	2025	Director and Corporate Senior Vice President, FUJIFILM Corporation

Becoming the most trusted semiconductor materials company by advancing the performance of individual products to reinforce the array of One-Stop Solutions

1

Offering One-Stop Solutions to implement a thorough customer-oriented approach

- Offering a broad-based product lineup and applying the principle of ‘local production for local consumption and local support’ to meet customer needs swiftly

2

Advancing the performance of individual products to maximize the problem-solving ability for customers

- Photoresists, CMP slurries, Polyimides, Color filter materials

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Fujifilm's semiconductor materials business markets Photoresists, CMP slurries and Polyimides as its growth drivers to strive to achieve the rate of growth far exceeding that of the semiconductor materials industry.

V.S.

Growth drivers

Photoresists	Developing the cutting-edge lineup with a focus on negative resists
CMP slurries	Leveraging our strength in CMP slurries for copper wires to expand the market share
Polyimides	Strengthening polyimides for advanced packaging

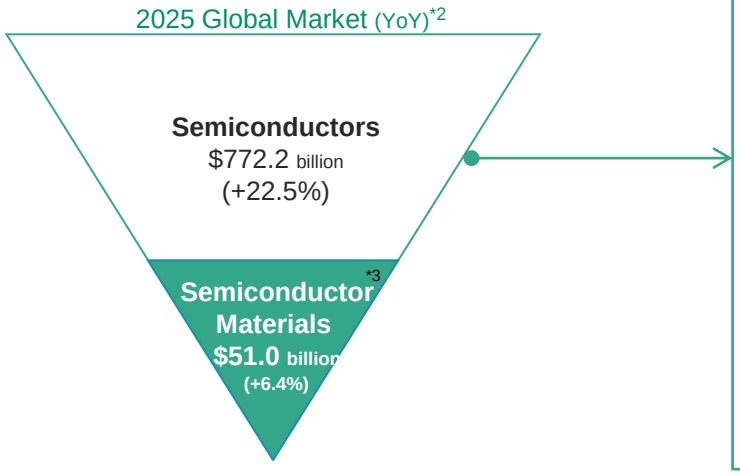
Etc.

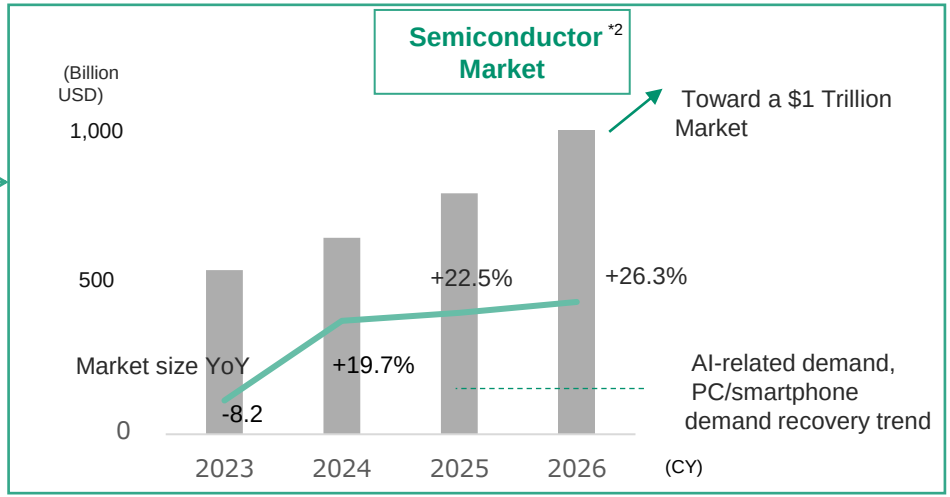
*Fujifilm estimation based on Fuji Keizai's report, "Current status and future outlook of the semiconductor materials market in 2025"

In 2025, driven by robust AI-related investment demand amid a recovery trend in the volume-driven smartphone and PC segments, the market will achieve double-digit percentage growth. Further expansion is anticipated beyond 2026, targeting a trillion-dollar market.

Semiconductor Market Trends

- 2025: Driven by robust AI-related investment demand, GPUs and HBM*1 lead the market, while smartphones and PCs in the volume segment show signs of recovery
- 2026 and Beyond: Continued robust AI-related investment will drive the market toward a trillion-dollar scale. Investment in next-generation technologies such as miniaturization and advanced packaging will intensify, driving further market expansion.





*1 High Bandwidth Memory (HBM)
*2Source: World Semiconductor Trade Statistics (WSTS) Autumn Semiconductor Market Forecast

*3 Source: Fuji Keizai Co., Ltd., "Current Status and Future Outlook of the Semiconductor Materials Market in 2025"

1-3 | International and inter-regional investment race for boosting semiconductor production

Semiconductor manufacturers' offshore expansion and risks of international / inter-regional supply chain breakup are accelerating the trend toward locally producing and consuming semiconductors. This is increasing the needs for "one-stop delivery" of uniform-quality products / services and " local support ".

Main international policy trends surrounding semiconductors

1 **Protect** **(protecting key technologies)**

US, EU, Japan and other countries and regions are **tightening export restrictions for China and domestic investment regulations** for some semiconductor materials and manufacturing devices.

2 **Partner** **(international and inter-regional partnership)**

Partnerships are expanding and deepening among high-presence countries and regions including US, EU, Taiwan, South Korea and Japan.

3 **Promote** **(promoting local industries)**

Semiconductor support policies are **diversifying** among countries and regions according to their local market's level of maturity, including subsidies directly connected to semiconductor production, R&D, taxation support and HR development.

Countries / regions	Feature	Description
US	**Focusing on strengthening the production foundation**	Supplying funds totaling US$52.7 billion over 5 years and reducing taxes by 35%
EU	**Focusing on strengthening the production foundation**	Planning public and private-sector investments worth 43 billion euros in cumulative total to 2030
Mainland China	**Providing a large-scale budget allocation**	Having government-affiliated semiconductor funds arrange funding worth 686.7 billion yuan (approx. 14.4 trillion yen) in the first – third total
India	**Establishing a production foundation and inviting foreign-capital companies**	Approving the plan to invest 1.6 trillion rupees in 2021 – 2025 to establish 10 semiconductor plants
Japan	**Adopting a strategy for balancing production foundation with future technologies**	Allocating 3.9 trillion yen in total budget for manufacturing and R&D in the semiconductor sector
Taiwan	**Investing in future technologies and HR development**	Promoting HR development in cutting-edge IC design and subsidizing R&D
South Korea	**Investing in future technologies and HR development**	Planning to expand university / graduate school intake for semiconductor-related departments and reinforce industrial / academic and bureaucratic collaborations through the next-generation intelligent semiconductor development project

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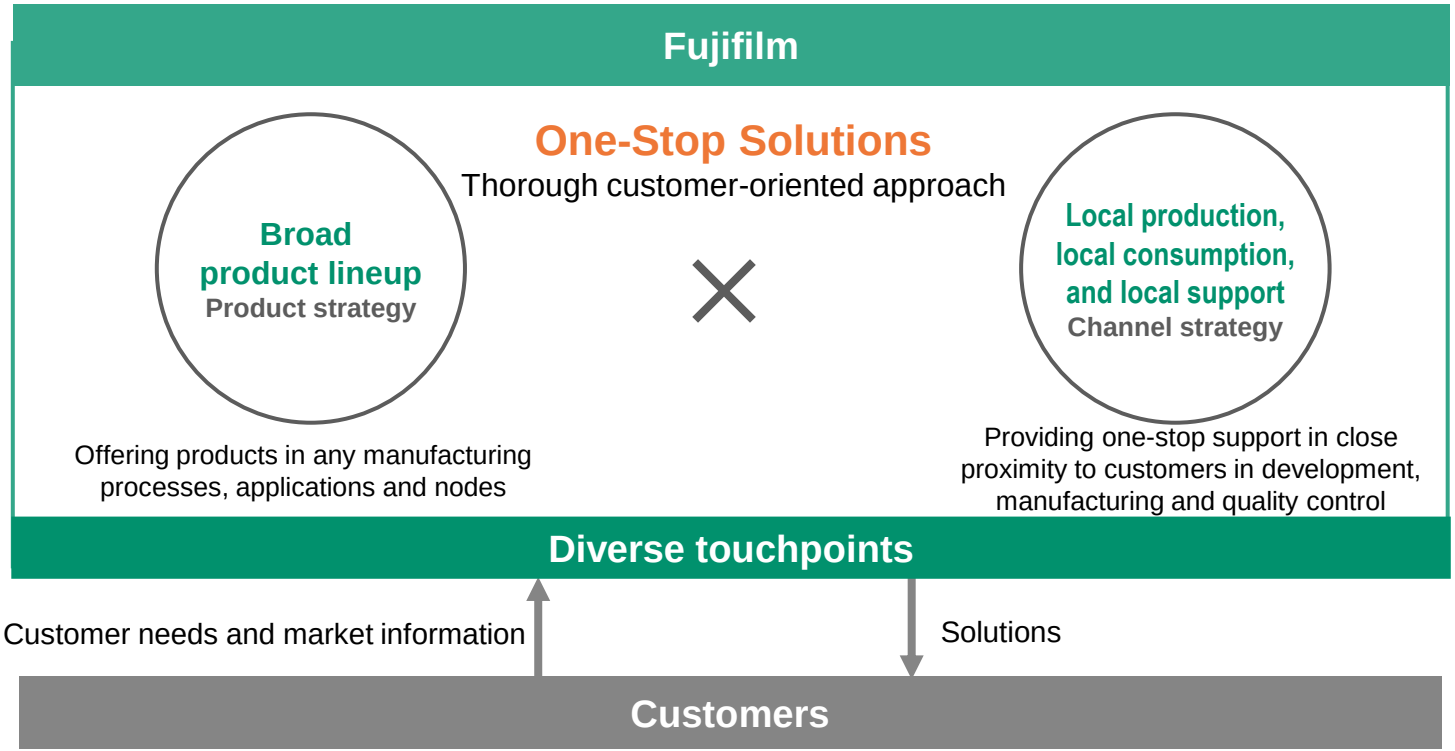
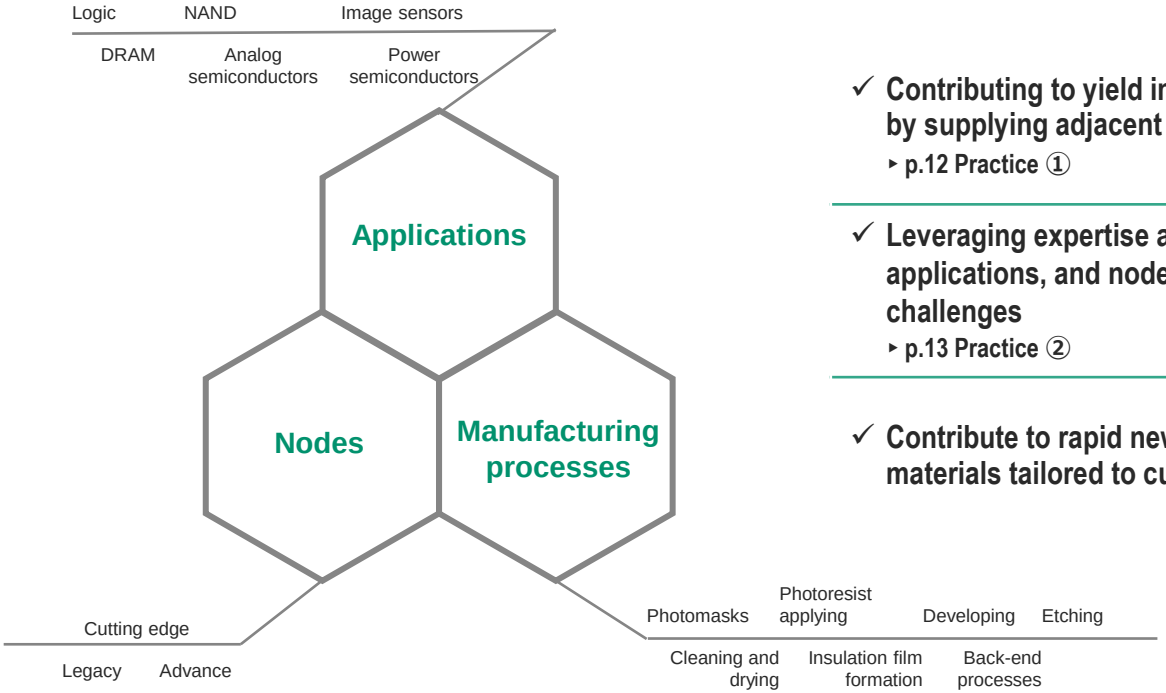
Offering a broad product lineup and using diverse customer touchpoints obtained through One-Stop Solutions across development, manufacturing and quality control, to swiftly identify the essence of customer needs and deliver solutions

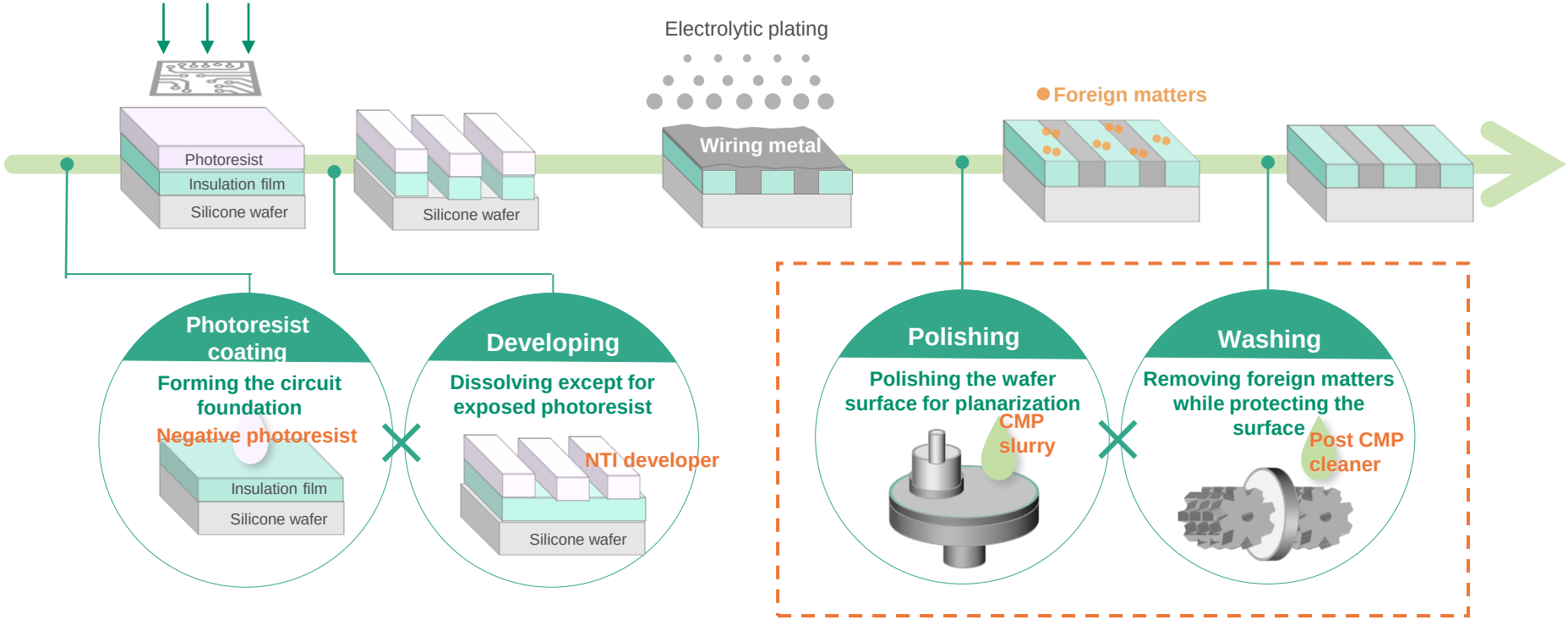


Offering a broad-based product lineup for all manufacturing processes, applications and nodes to cater to any customer needs and combining products to formulate solutions for customers



- ✓ **Contributing to yield improvement through synergistic effects by supplying adjacent process products as sets**
  ▸ p.12 Practice ①
- ✓ **Leveraging expertise across all manufacturing processes, applications, and nodes to propose solutions for customer challenges**
  ▸ p.13 Practice ②
- ✓ **Contribute to rapid new line launches by providing all proven materials tailored to customer needs** ▸ p.14 Practice ③

Providing materials for adjacent processes as a set contributes to improved yield through the synergistic effects of each material.



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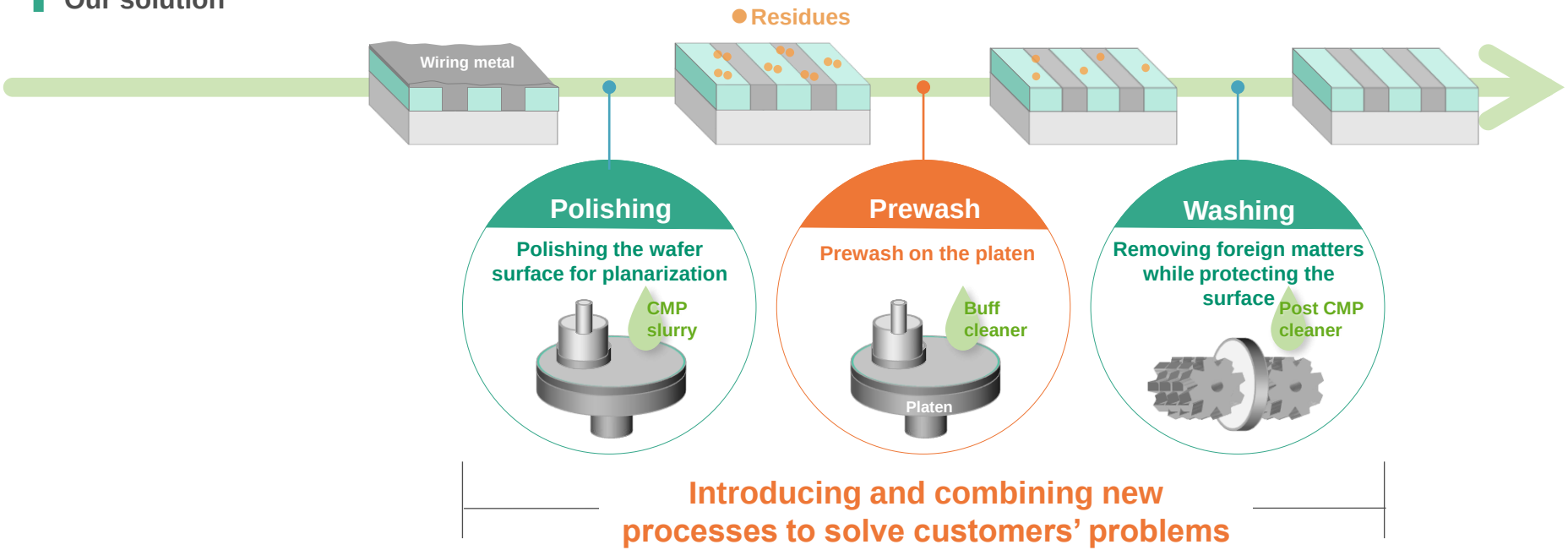
Leveraging insights from adjacent processes, we propose material combinations and new processes to solve customer challenges

- **Customers' problems：** With miniaturization, we aim to further reduce post-polishing residue.
- **Our solution**



Offering a broad-based product lineup to deliver One-Stop Solutions that assist new business launches amidst the emergence of new semiconductor manufacturers leveraging low costs and active government assistance, mainly in Asia's emerging economies

Customers' problem： **Using materials that have been used before to launch production lines swiftly**

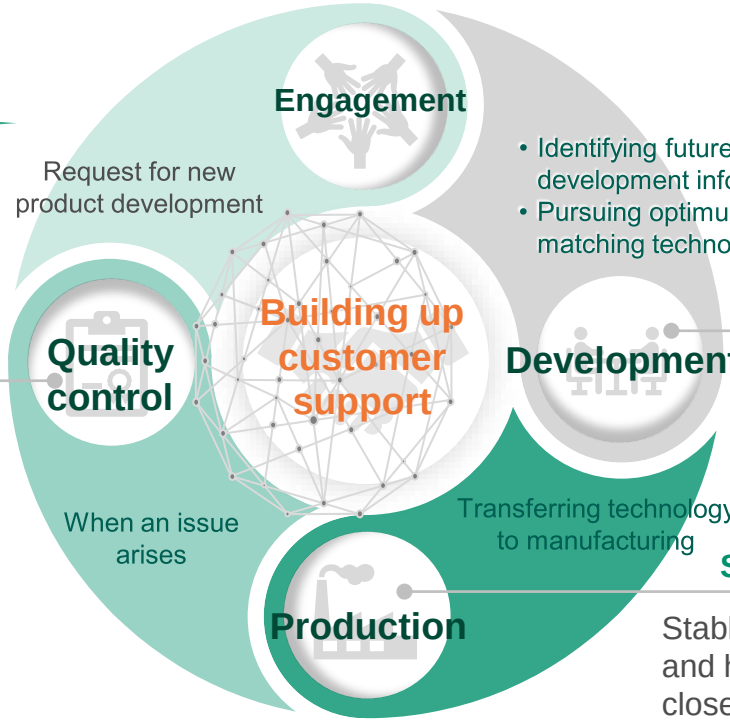
Asia, US, Europe

Leveraging technologies and know-hows fostered through business association with major semiconductor manufacturers to expand new customers in the mainland China and India

	Photoresists	Photolithography material	CMP	Insulation films	Others
Company A (US)	✓	✓	✓	✓	…
Company B (South Korea)	✓	✓	✓	✓	…
Company C (EU)	✓	✓	✓	✓	…
Company D (EU)	✓	✓	✓	✓	…

Having engineers, stationed near customers, communicate in the same language to provide one-stop support from development to production and quality control, thereby contributing to development and stable operations that meet customers' needs

Support in the language customers use



- Identifying future generations' development information
- Pursuing optimum solutions with matching technologies

Priority 1

Information gathering and analysis

Development Working with customers to cater to their needs closely

Priority 3

Swift response to issues

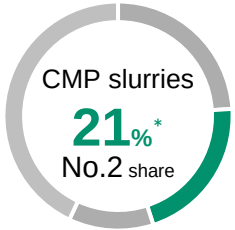
Generous support from engineers stationed near the local plant

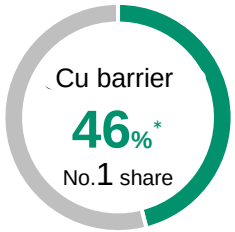
Priority 2

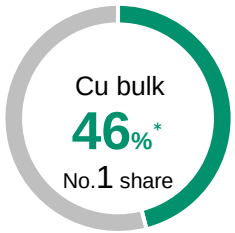
Stable supply structure

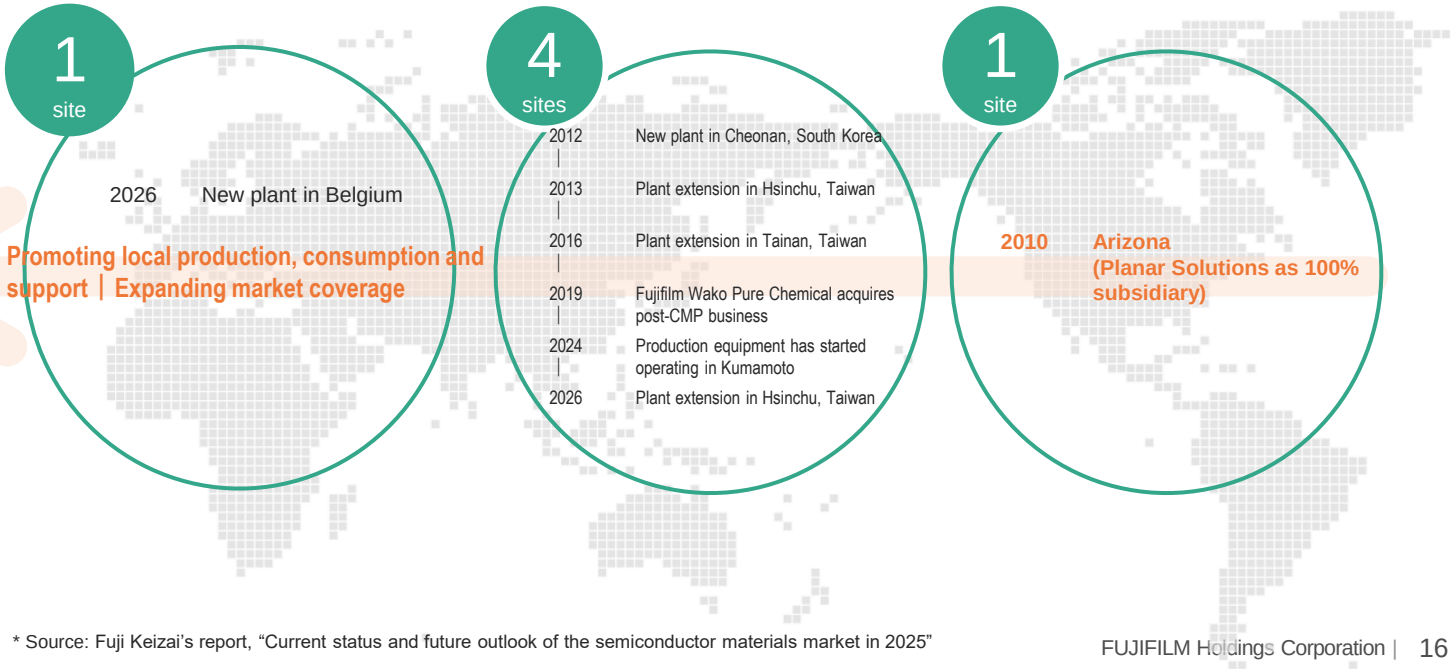
Production Stable supply and BCP support of uniform and high-quality products from regions in close proximity to customers

Turning the Planar Solutions, originally established in 2000 for developing CMP slurries for use with copper wires, into a 100% subsidiary in 2010, and building new plants in Asia and EU to promote local production, consumption and support for building up trust



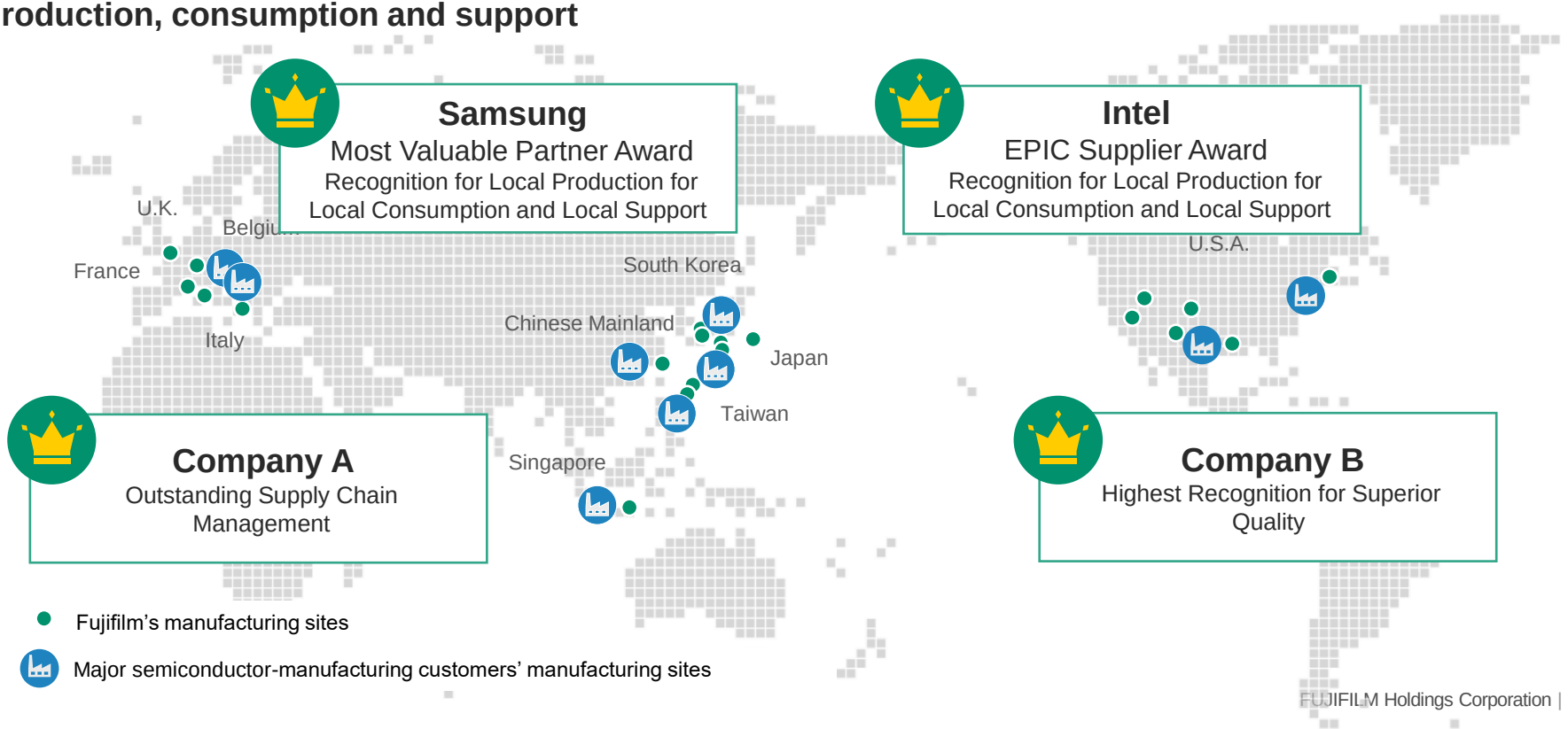






* Source: Fuji Keizai's report, "Current status and future outlook of the semiconductor materials market in 2025"

Winning a supplier award from multiple major semiconductor manufacturers, who appreciate our efforts to build a robust supply chain structure based on global production and R&D sites for local production, consumption and support



Accelerating the pace of investments from FY2025 to FY2026 to further strengthen the structure of local production, consumption and support

Cumulative investment total * (2021～2024)

¥100 bn or more over 4 years

FY2021	e.g. Arizona and Rhode Island States, USA
FY2022	e.g. Shizuoka, Japan
FY2023	e.g. Kumamoto, Japan and Flanders, Belgium
FY2024	e.g. Shizuoka, Japan and Tainan, Taiwan

Planned investments * (2025～2026)

¥100 bn or more over 2 years

*Capital expenditures and R&D expenses

FY2025	e.g. Shizuoka, Japan and Flanders, Belgium
FY2026	e.g. Oita, Japan and Hsinchu, Taiwan

Accelerating the pace of investments

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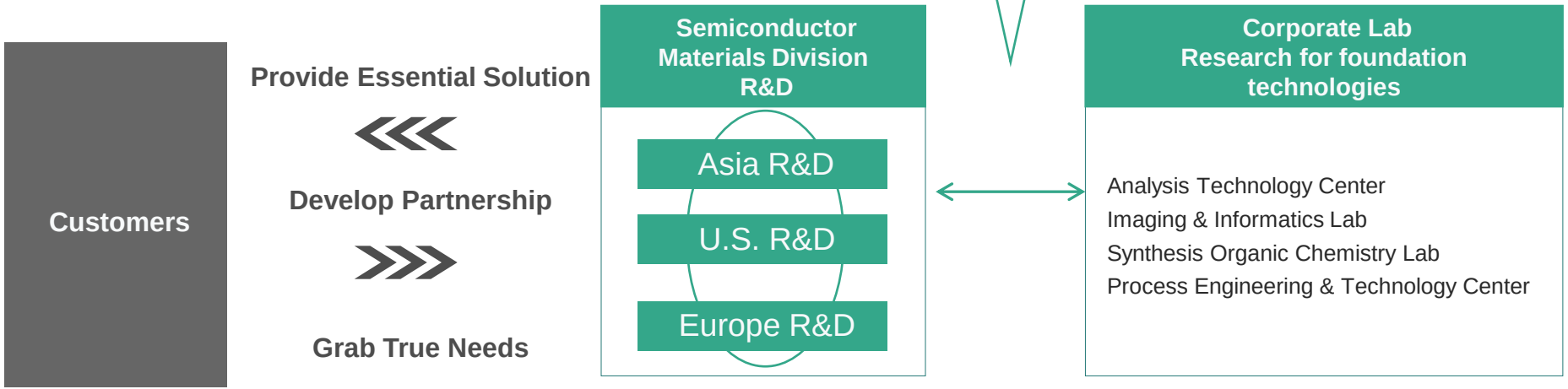
By collaborating with corporate labs and coordinating across R&D sites, we provide solutions that address the core issues accurately identified through direct communication with customer technical departments at R&D centers worldwide.

- ✓ Application to product design such as "functional molecular technology" and "nanodispersion technology"
- ✓ Application of Advanced Analytical Techniques to Quality Control and Quality Assurance, and Resolution of Technical Challenges in Development
- ✓ Utilization in AI/IT Research and Development ▸ p.21–p.23
- ✓ Application of "Precision Coating Technology" accumulated through years of film production ▸ p.43



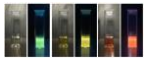
By introducing AI into Fujifilm technology that manages and controls material structures at the Å~mm scale to ensure high quality, Fujifilm adds further value such as shortening R&D lead times and improving quality.

Examples of Fujifilm Proprietary Libraries
(Accumulation of Fujifilm Technology and Expertise)

(1Å) 0.1nm | 1nm | 10nm | 100nm | 1μm | 10μm | 100μm | 1mm

Electronics & Molecules
Colorants/Dyes

Pharmaceuticals

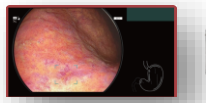

Organic Materials
Quantum dots

Silver Halide Film/Print

Inorganic Materials
Sensor Materials


Polymer Resins
Flat Panel Materials
Semiconductor photosensitive materials

Composite Inks


Films & Membranes
Recording media


Devices
Endoscope
Image diagnosis support


Systems
Optical Lenses

Multifunction device


×

AI

- ✓ Predicting material composition and formulations that meet customer requirements
- ✓ High-precision detection of nano-level abnormalities
- ✓ Proposing more appropriate materials and formulations through machine learning

Shortening R&D Lead Times, Further Quality Improvement

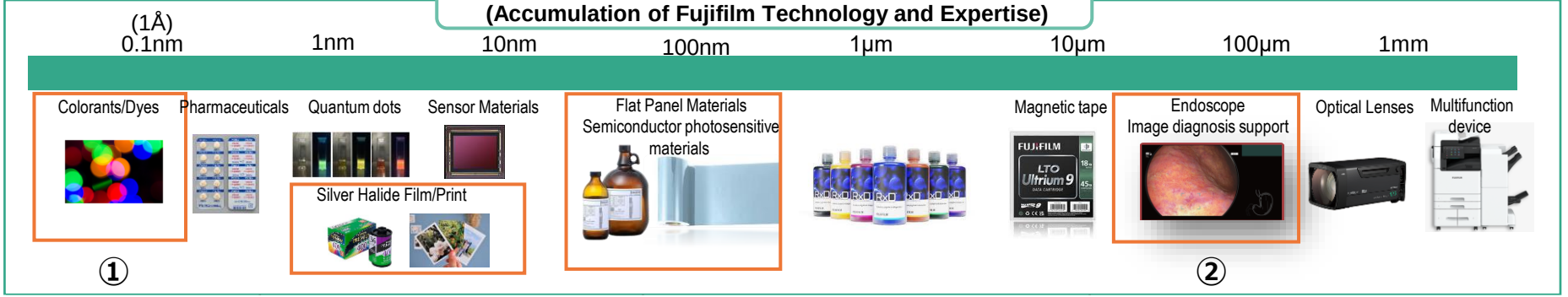
By introducing AI into thermal simulation technologies cultivated through multifunction devices and ink, we will rapidly develop new products that contribute to improved product quality and layered manufacturing.

Examples of Fujifilm Proprietary Libraries
(Accumulation of Fujifilm Technology and Expertise)

	Library	AI Utilization	Effect
Thermal Stress Evaluation	① & ③ Multifunction Device Thermal Simulation	Material composition and formulation prediction tailored to the customer's usage environment	Rapidly explore candidate materials for use in multilayer structures
Dielectric layer pattern automatic measurement	② Image measurement technology	Detecting fluctuations in the fine line width of the formed electrical circuit	Improved Quality Through Enhanced Inspection Accuracy

By introducing AI into color control technologies cultivated through silver halide photography, we rapidly develop materials for high-definition, high-sensitivity image sensors.

Examples of Fujifilm Proprietary Libraries
(Accumulation of Fujifilm Technology and Expertise)



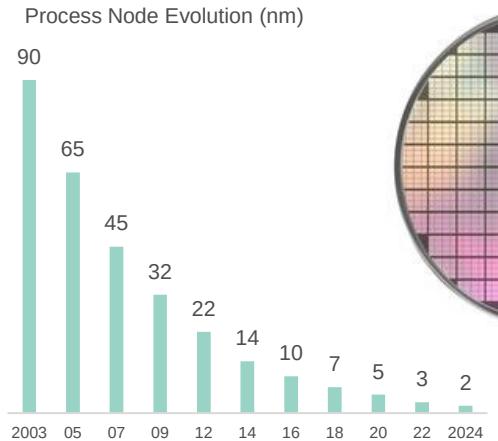
	Library	AI Utilization	Effect
Spectroscopy	① Color Control Technology	Predicting pigment combinations and concentrations that meet customer requirements	Shortening Development Lead Time Achieving High-Transmittance, High-Contrast Images
Automated defect inspection	② Image recognition technology	Detection of minute defects	Improved accuracy in identifying defect causes contributing to fine pixelization and shortening development lead times

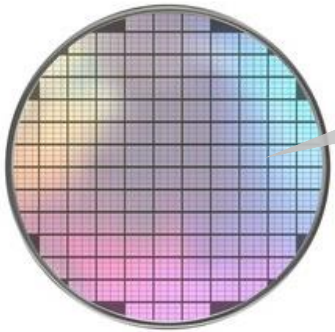
Other
The development of light-resistant dyes cultivated through silver halide film and functional molecular design technologies honed through materials for flat panel displays also contribute to the development of image sensor materials.

While miniaturization has historically driven semiconductor performance improvements, rising technical hurdles and increasing costs have heightened the importance of functional integration in back-end processes utilizing front-end technologies. We are focusing on new material development by leveraging our strengths.

Front-end Process

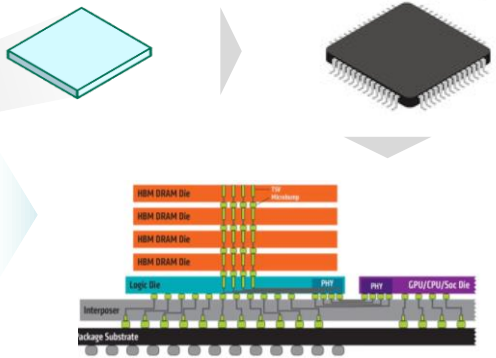
Forming circuits on wafers





Back-end Process

Dicing, Assembly, and Packaging



Increased Costs in Miniaturization

Utilization of front-end process technologies

Focus on Package Assembly Technology (High-Functionality/High-Integration)

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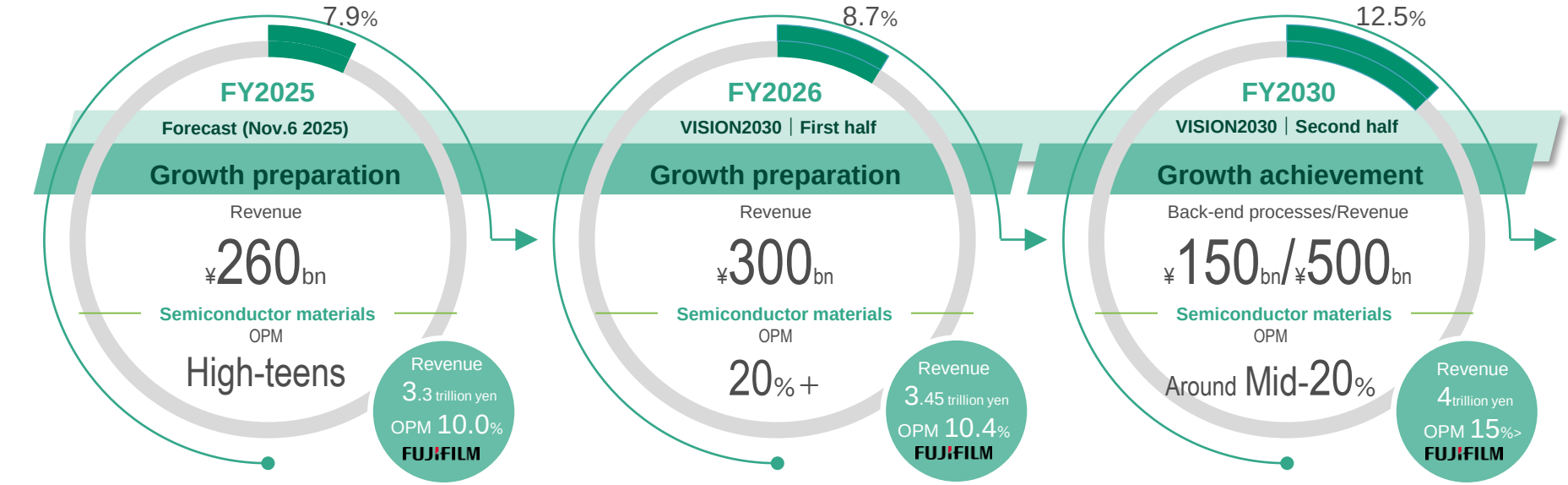
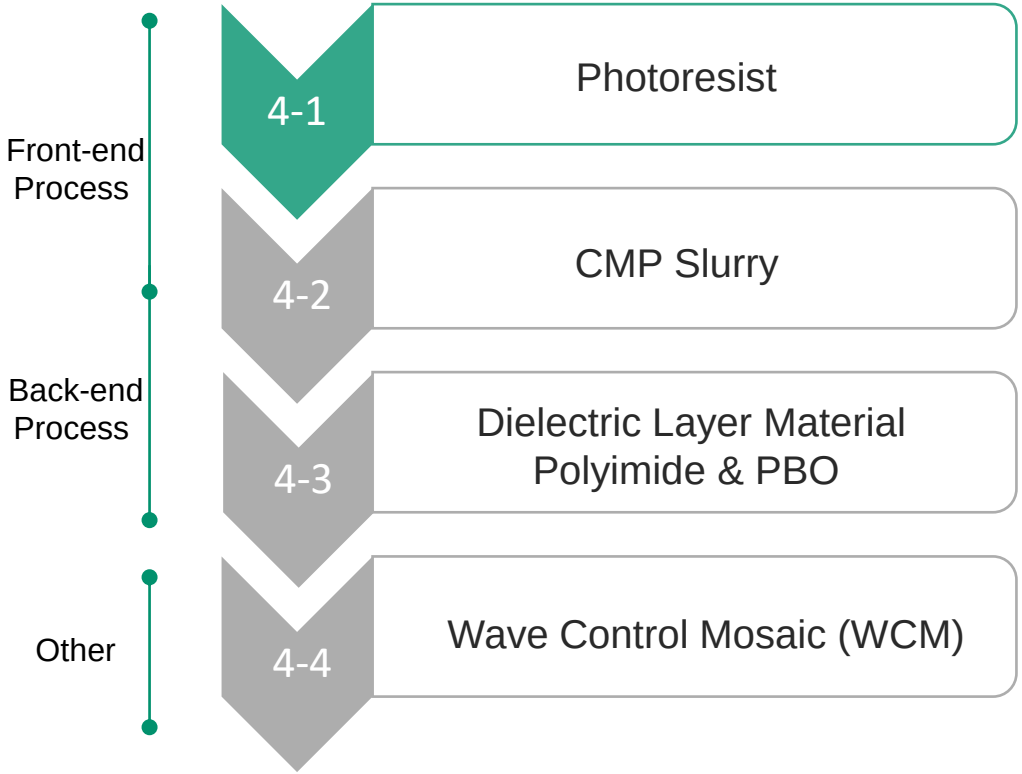
Offering a broad-based product lineup, applying the principle of 'local production for local consumption and local support' to provide One-Stop Solutions and promoting the development of new materials to reach the net sales of ¥500 bn (incl. ¥150 bn from back-end processes) and OPM of around mid-20% by FY2030

Ratio of semiconductor materials in Fujifilm's consolidated Revenue

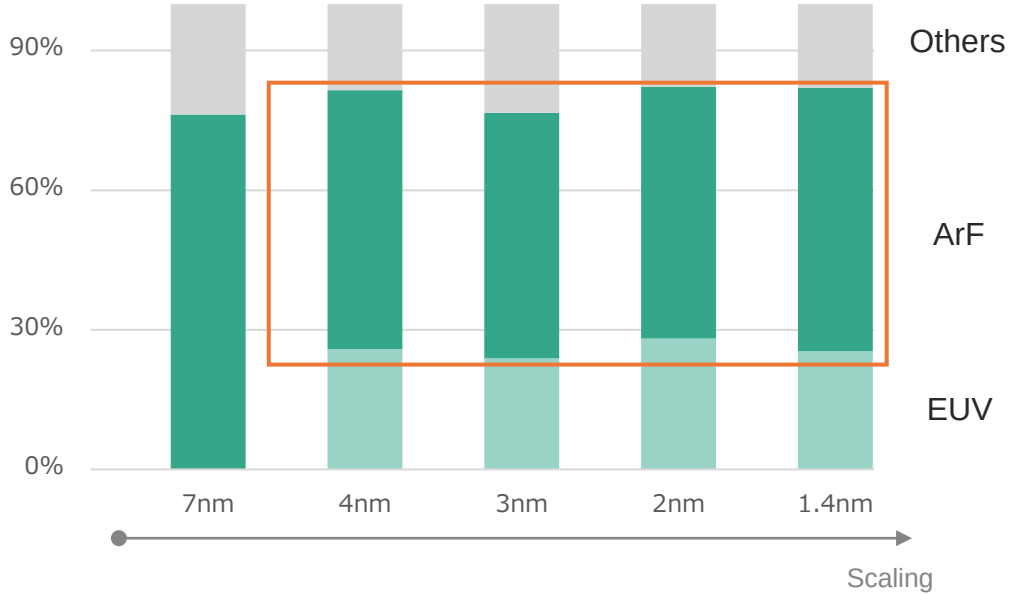


Maximize our ability to solve customer challenges through One-Stop Solutions by enhancing the performance of individual products such as photoresists, CMP slurries, and polyimides



The composition ratio of ArF resist in a total number of resist coating by 2030 is expected to remain very high even at fine nodes, and the volume of ArF resist is expected to expand due to semiconductor market growth and advancing miniaturization.

ArF/EUV resist composition ratio of resist coating in 2030 (by Node) *



* Our estimates

Amid steadily increasing inquiries, applying EUV resist's new technology to ArF resist will accelerate growth, aiming to achieve a 20% share in advanced resist by 2030

*Includes EUV/ArF/KrF/EB/Nanoimprint and others

	Progress	Future Developments
EUV/ArF	Inquiries increased 4-5 times compared to last year	Applying new EUV technology to ArF for further performance enhancement ▸ Next page
KrF	Secured adoption in advanced image sensor projects	Continued niche leadership in image sensor applications
Nanoimprint Lithography (NIL)	Currently under evaluation, primarily by logic manufacturers	Collaborating with NIL equipment manufacturers to develop photoresists and bonding agents
Environmental Compliance	Developing PFAS-free negative immersion ArF resist Also applicable to KrF; customer sample evaluation underway	Applying PFAS-free to all resists ▸ p.31

By applying the EUV resist technology "PCP technology" to ArF resist and suppressing line width fluctuations, we have achieved further high performance in negative-type ArF resist with high patterning accuracy.

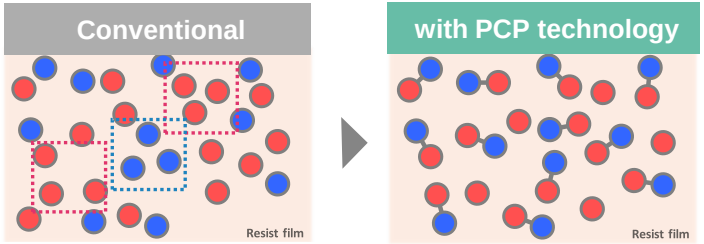
Coating → Exposure → Bake → Development

Application of EUV's new "PCP" technology

Achieves more uniform and sharper line width patterning through uniform reaction

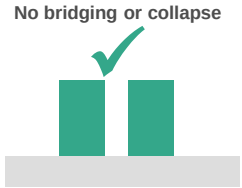
PAG — PDQ

✓ Synthesizing a new PCP structure (PAG Connected PDQ) by combining PAG (Photo Acid Generator) and PDQ (Photo Degradable Quencher), achieved uniform distribution within the film

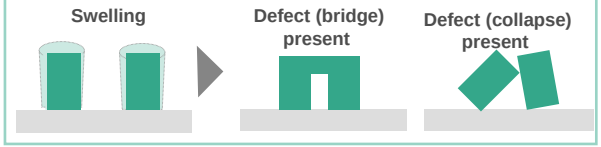


Use of NTI* developer

Suppresses swelling and achieves high patterning accuracy



Example of defect occurrence due to swelling



∗ Negative Tone Imaging : Developer used in the process (the negative-type development process that removes unexposed areas with developer to form circuits)

We developed a PFAS-free negative ArF immersion resist, expanding our lineup to meet customers' environmental compliance needs.

Performance evaluation results with imec* demonstrate the ability to form 28nm generation metal wiring with high yield

Organic Synthesis Technology
Based on synthesis know-how
Designing unique molecular structures

+

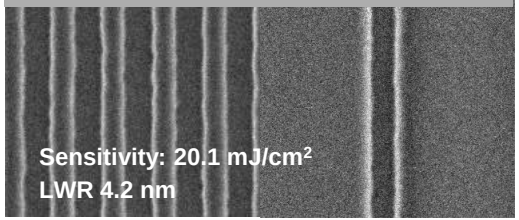
Formulation Technology
Leveraging extensive expertise
We carefully formulate material compositions

+

Analytical Technology
Clarifying functional activation mechanisms through phenomenon analysis and theoretical calculations

✓ **Excellent lithography performance equivalent to conventional products**

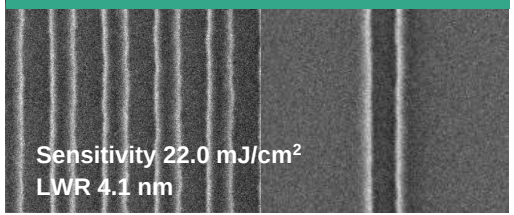
Conventional product containing PFAS



Line width 45 nm
Pitch 90 nm
Line-space

Line width 45 nm
Isolation space

Newly Developed Product PFAS-Free

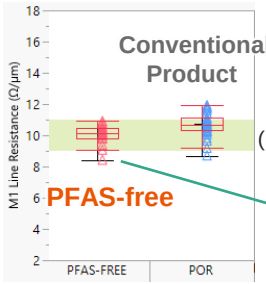


Line width 45nm
Pitch 90nm
Line Space

Line width 45nm
Isolation Space

✓ **Electrical characteristics equivalent to or better than conventional products**

Example of Electrical Characterization Test Results

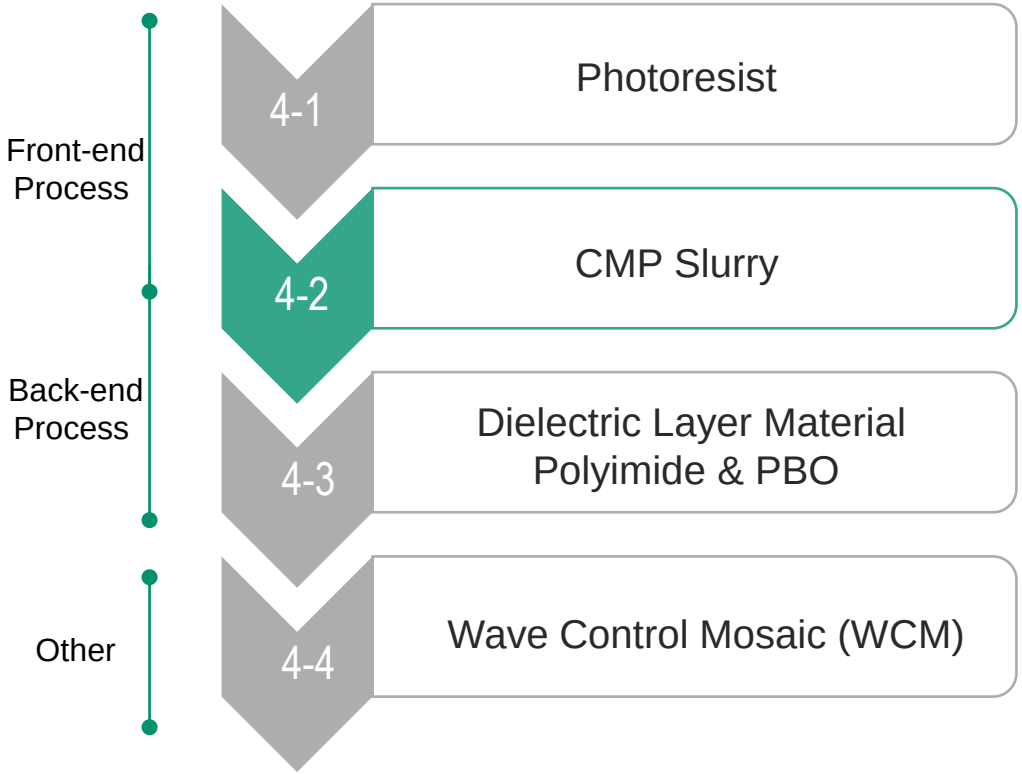


imec M1 layer line resistance
(Line width 45nm, Line length 100μm)

Electrical resistance equivalent to or lower

*Abbreviation for Interuniversity Microelectronics Centre. The world's largest research institute in the field of nanoelectronics and digital technology, located in Belgium

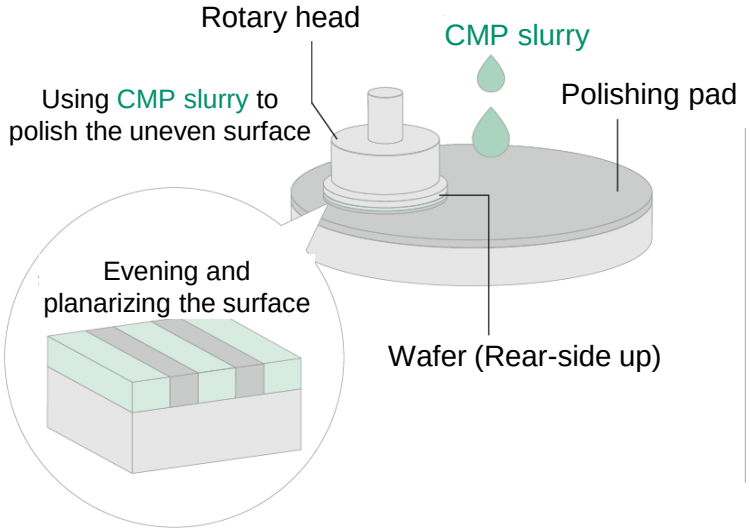
Maximize our ability to solve customer challenges through One-Stop Solutions by enhancing the performance of individual products such as photoresists, CMP slurries, and polyimides



Amidst the recent trend to adopt a 3D structure in semiconductor manufacturing, there is an increasing significance to the CMP process, which involves evenly planarizing the wafer surface with “chemical agents” for changing and dissolving the surface and “abrasive grains” for physically polishing the surface.

CMP = Chemical Mechanical Polishing

Using slurry that contains chemical agents and abrasive grains to apply both chemical and mechanical actions to polish and planarize the wafer surface.



Principle of CMP

Chemical action
Chemical agents

Chemical agents are used to **change the property of and dissolve the polishing surface** to assist mechanical polishing with abrasive grains.

【Main chemicals】
pH-regulator, oxidizer, stabilizer etc.

×

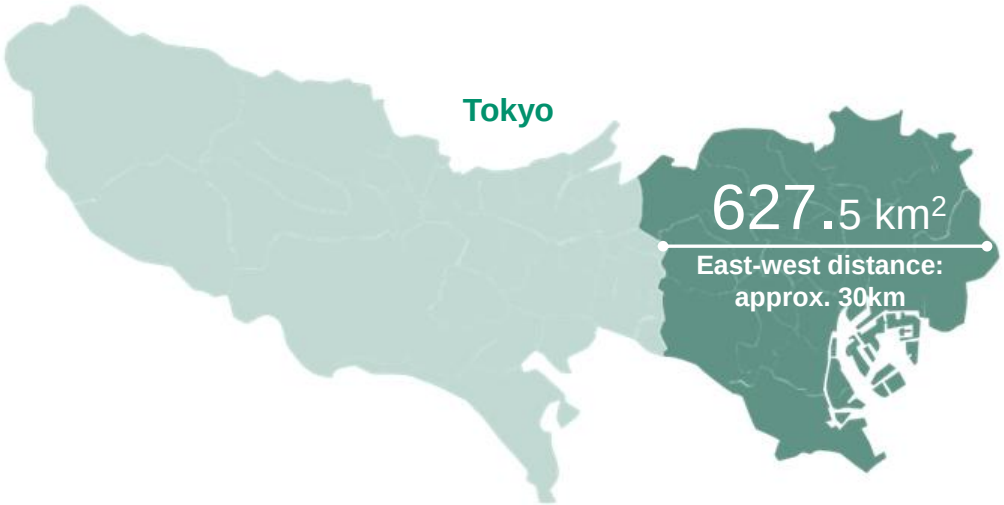
Mechanical action
Abrasive grains

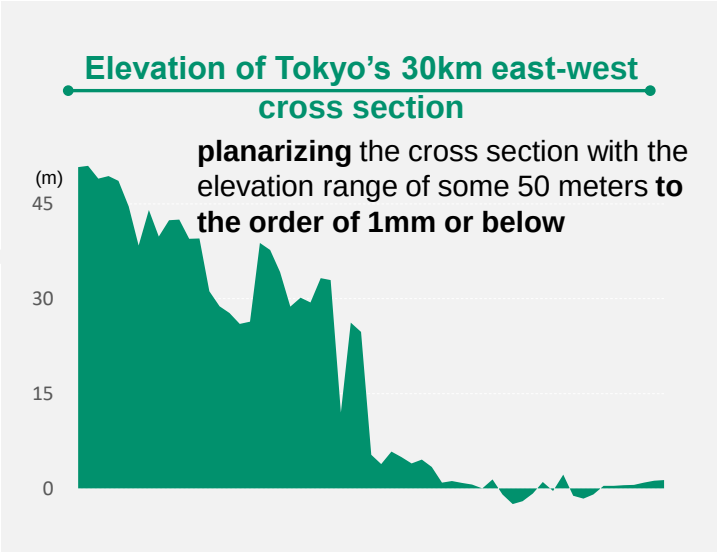
Abrasive grains in the slurry are used to **mechanically polish the surface**.

【Main polishing elements】
Silica (SiO_2), alumina (Al_2O_3)、ceria (CeO_2) etc.

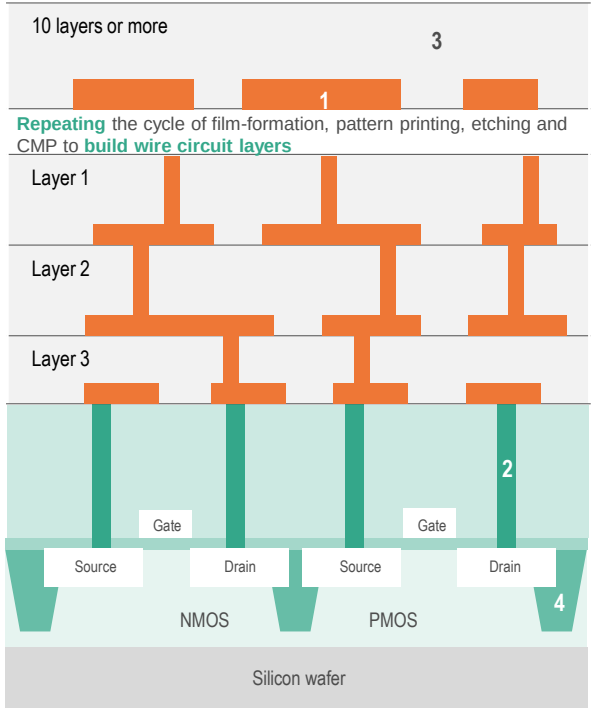
CMP planarization is an important process that requires <u>planarizing the surface of 300mm wafers to the level in the order of several nanometers</u>

= Precision equivalent to planarizing the unevenness of the 23-ward central Tokyo to the order of 1mm





CMP slurries is the essential material for semiconductor circuit miniaturization and densification, come in different compositions depending on targeted surface materials.
Fujifilm has the No.1 market share for copper wire applications.

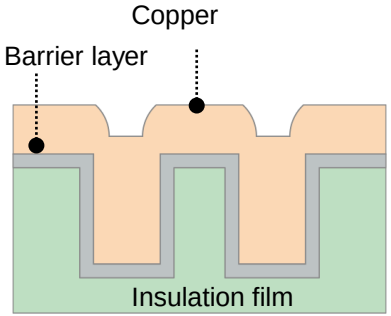


CMP slurries marketed by Fujifilm hold
No.1 market share in the copper wire sector*

		Process		CMP Market Ratio*	Role	Materials	Abrasive Grain
1	For wiring layers	Copper wiring layer	Cu bulk	20%	Currently a mainstream wiring material for transmitting electromechanical signals	Copper (Cu)	Silica
			Cu barrier	25%		Ta, TaN (Barrier Metal)	
2		Tungsten Layer		17%	Filling contact holes and VIA holes	Tungsten (W)	Silica
3	Interlayer Insulation Film	Interlayer Insulation Film (ILD)		21%	Providing electric insulation between layers of different wirings	Oxide film	Silica, etc.
4		Device isolation Film (STI)		11%	Preventing electric interference between transistors and other elements	Oxide film	Ceria, etc.
5	Other			6%			

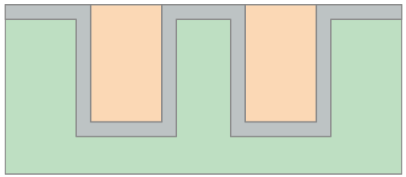
* Source: Fuji Keizai's report, "Current status and future outlook of the semiconductor materials market in 2025" 2024 Sales trends by type

Fujifilm's CMP slurries combine three proprietary technologies, i.e. ① Chemical-formula optimization technology, ② high-density dispersion technology for abrasive grains and ③ non-selective polishing technology, Those could deliver outstanding performance, enabling quick and precise polishing quality that satisfies customers' needs



Bulk slurry

Polishing copper



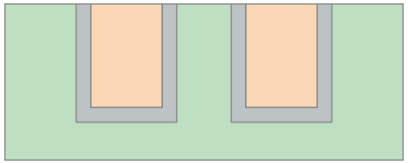
① Formula optimization
Optimizing the formula of abrasive grains, which work with etching agents, preservatives and other chemicals to physically grind and polish the target

② High-density dispersion technology for abrasive grains

→ Planarizing copper quickly and at high precision

Barrier slurry

Polishing the barrier layer, copper and insulation film



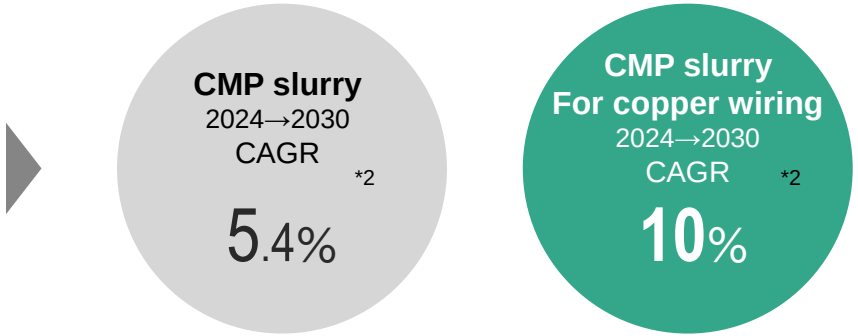
③ Non-selective polishing technology
Regulating the polishing of copper, barrier layers and insulation films for planarization in the order of nanometer

→Customization to suit customers' needs in the order of nanometer level

Further nano-level fine patterning and increment of the stacking layer bring to increase the number of wiring layers, and technological advancement will incorporate the use of advanced packaging technology. These lead to the increase in CMP slurry use, with their use for copper wiring anticipated to grow at CAGR 10%.

Increased usage due to miniaturization and multilayering

- Increase in the Number of Wiring Layers in Advanced Logic
- Increase in the number of wiring layers in DRAM
- Changes in transistor structure
- Changes in power supply methods (BSPDN) *1
- Use for polishing new metal wiring with improved electric efficiency
- Addressing new technologies used in the back-end process (Hybrid bonding, etc.)



*1 Back Side Power Delivery Network: Technology for placing the power supply network on the back side

*2 Fuji Keizai Co., Ltd. "Current Status and Future Outlook of the Semiconductor Materials Market in 2025" 4. Sales Trends by Type 1) Overall Type-by-Type (Global Market, Value Basis) Based on 2024 (Actual) Data, Our Company's Calculation

Aiming to more than double CMP slurry revenue by FY2030 to achieve the No.1 market share by leveraging our technological capability as the segment leader in copper-wire CMP slurries and adopting the approach of local production, consumption and support

For advanced logic semiconductors

Expanding sales for advanced nodes and developing CMP slurries for new metals

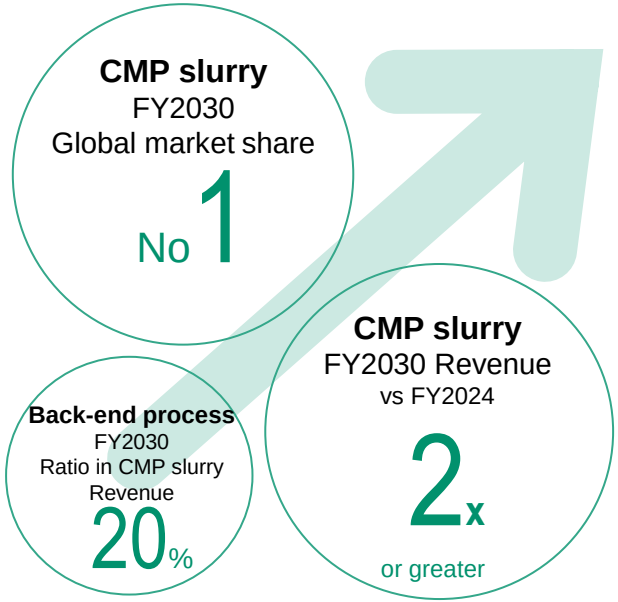
For memory semiconductors

Expanding sales for advanced devices, especially HBM*, whose demand is booming due to generative AI

＊High Bandwidth Memory

Advanced packaging area (Back-end process)

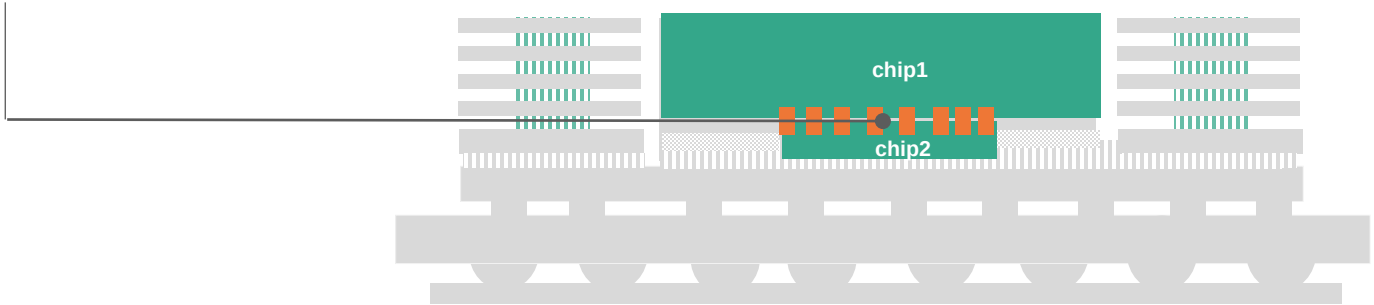
Gaining applications in "hybrid bonding" "re-distribution layers (RDL) formation" and "micro-bump bonding" processes



Major semiconductor manufacturers have decided to adopt Fujifilm CMP Slurry for their advanced packaging technology, "hybrid bonding", and the evaluation is undergoing for adoption in next-generation semiconductors such as HBM

What is hybrid bonding?

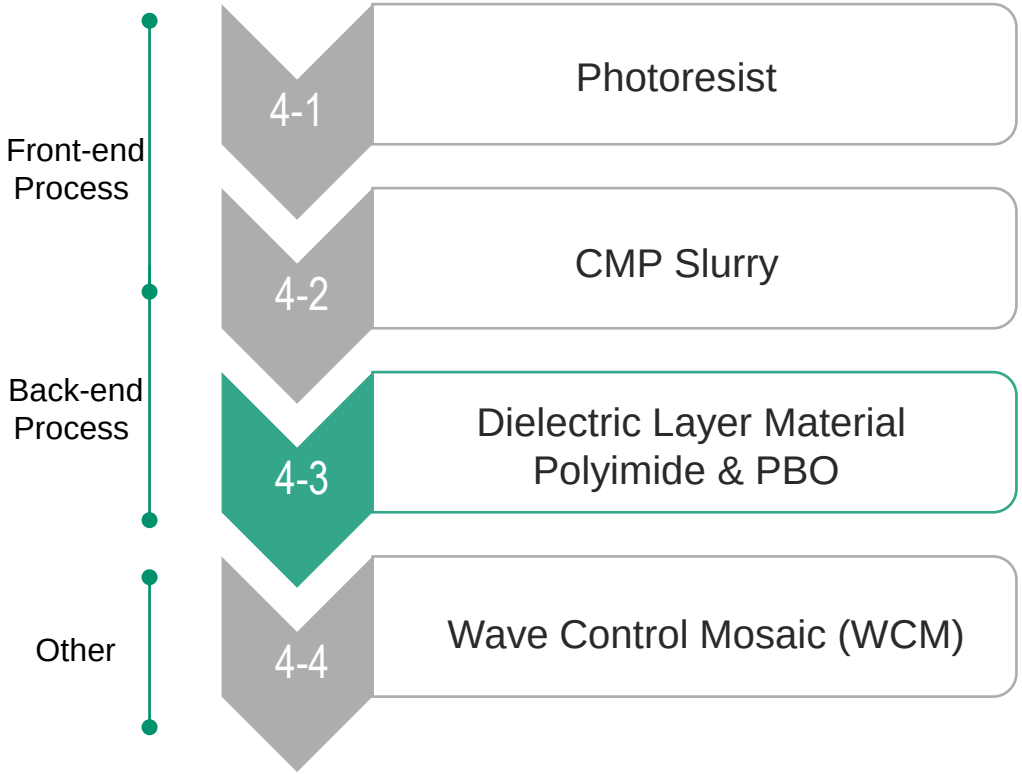
One of the most advanced semiconductor packaging technologies. A connection technology for directly bonding multiple chips or wafers at high density.



Fujifilm Progress

NAND	✓ **Adopted by major semiconductor manufacturers** Optimized formulation of additives, corrosion inhibitors, abrasive grains, etc., based on **CMP slurry for copper wiring** →High-precision planarization of bonding surfaces containing a mixture of **copper** and oxide film
DRAM	✓ **Currently undergoing sample evaluation by major semiconductor manufacturers for HBM**

Maximize Fujifilm ability to solve customer challenges through One-Stop Solutions by enhancing the performance of individual products such as photoresists, CMP slurries, and polyimides



Fujifilm will satisfy the customer needs in the distribution layer material by polyimide, both liquid-type and film-type which is under development.

Role of dielectric layer material: **Utilizing its heat resistance and electrical properties, it is used for chip protection and re-distribution layer**

Liquid-Type polyimide		Under development Film-Type polyimide	PBO(Polybenzoxazole)
LTC series	Durimide™ Series		FB series
Re-distribution Layers (Fan-out、Interposer)	**Protection Layers** Buffer Coat(Cushioning material) (for Power Semiconductor)	**Re-distribution Layers** (Build-up substrates , Interposer)	**Protection Layers** **Buffer Coat(Cushioning material)** (for Power Semiconductor)

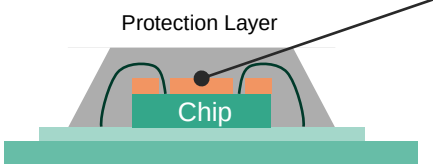
Dielectric layer material (Liquid + Film) Market 2024→2030 CAGR
15% *1

▸ Next Page

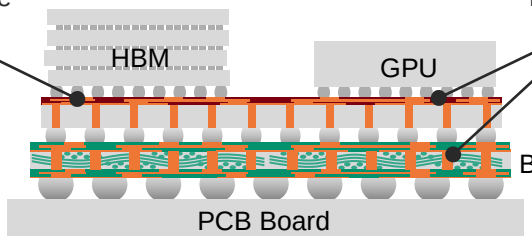
Liquid-Type Polyimide

Film-type polyimide

▸ p43



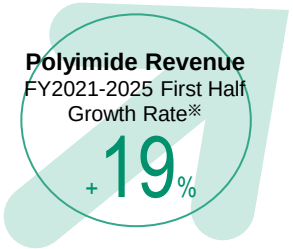
Protects chips from physical and chemical damage



Used as an dielectric material for forming re-distribution layers

*1 Company estimate

Driven by liquid polyimide—capable of meeting all performance demands from automotive applications to advanced packaging required for generative AI—polyimide is steadily achieving sales growth



Strengths of Fujifilm Liquid Polyimide

- ✓ A broad product lineup meeting customer demands, from power semiconductors to AI semiconductors
- ✓ Stable supply system with manufacturing bases in Japan, the U.S., and Europe
- ✓ Extensive adoption by OSATs and power semiconductor manufacturers

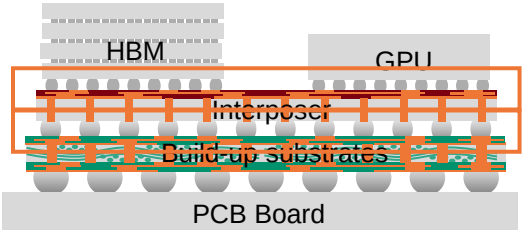
FUJIFILM has developed film-type polyimide from our reliable liquid-type polyimide materials, by utilizing our original precision-coating technology. This could contribute advanced packaging products area and enhance further new application development in the customers.

Customer Challenge

① Develop the fine pattern wiring and higher stacking in interposer and build-up substrates

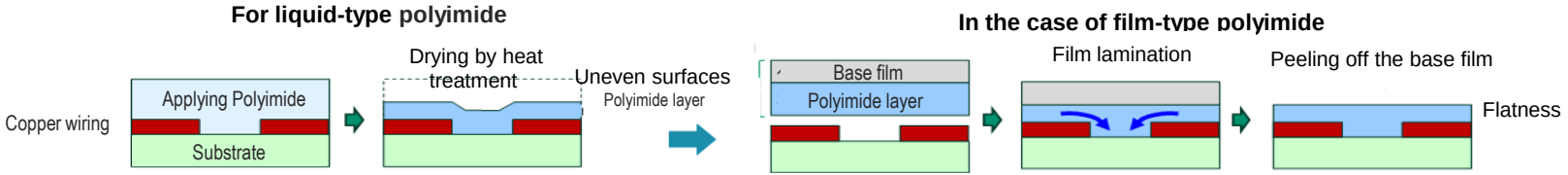
② Improvement the yield rate in panel-level packaging manufacturing*

*Technology for batch manufacturing packages by mounting multiple silicon dies on a panel substrate larger than a wafer

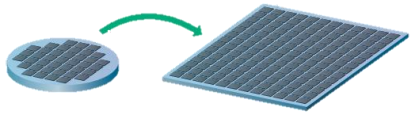


Solution

① Realizes flatness using film-type polyimide. In addition, proprietary formulation technology enables the formation of fine wiring patterns, contributing to miniaturization and higher stacking.



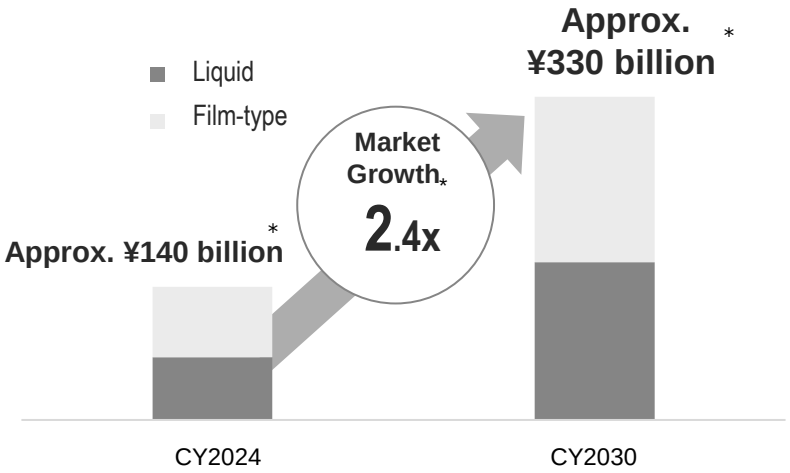
② Film-type provides stable processability for large panel sizes , where uniform coating using liquid-type polyimide is difficult, thereby contributing to yield improvement.



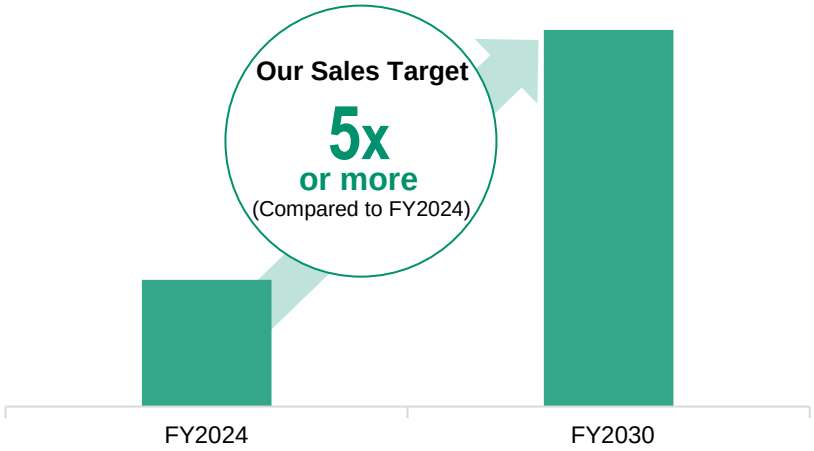
Currently undergoing sample evaluation for clients in Asia and major cloud service providers

By further promoting the adoption of liquid-type polyimide tailored to customer needs and realizing mass production of film-type polyimide, we aim to increase sales to more than five times the FY2024 level by FY2030.

Dielectric Layer Market Forecast



Dielectric Layer Materials Sales Target



*Company estimate

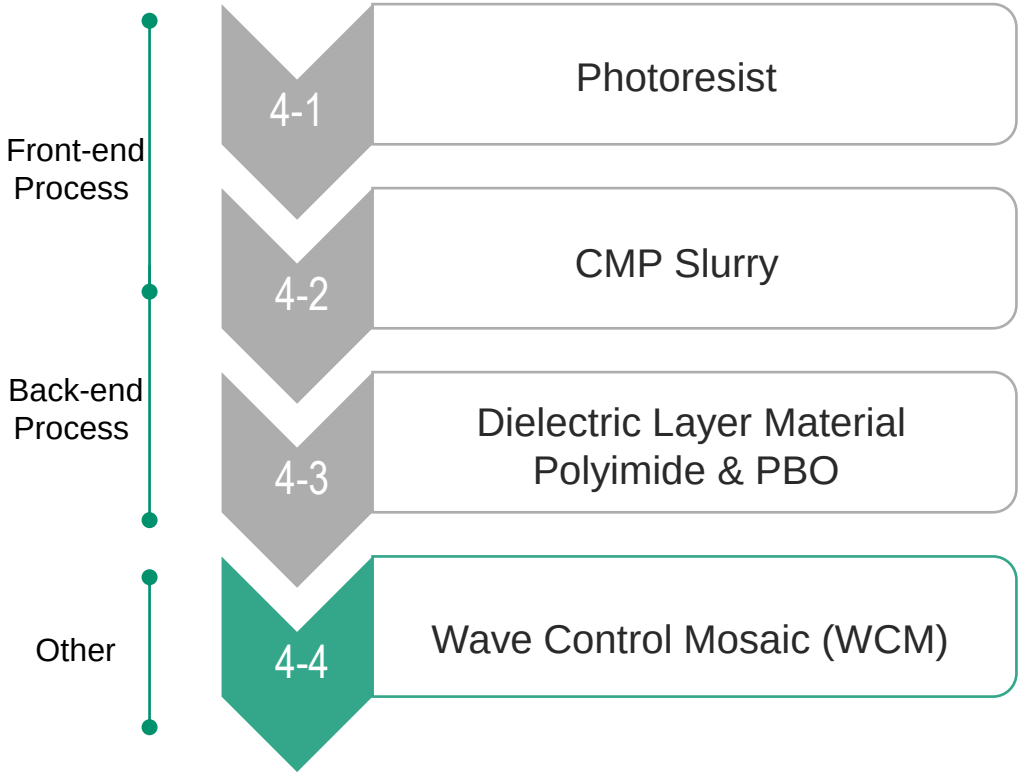
Under our photosensitive dielectric layer material brand, "ZEMATES," we consistently provide high-quality materials and continue to be a trusted partner for our customers.

ZEMATES™

The Vision Behind the Brand

**By providing highly reliable materials,
we aim to support the future of the semiconductor industry together with our customers and drive innovation.
We strive to remain a trusted partner and ally.**

Maximize our ability to solve customer challenges through One-Stop Solutions by enhancing the performance of individual products such as photoresists, CMP slurries, and polyimides



Among WCM image sensor*1 materials, which detect light from the visible to the invisible spectrum, the color filter materials for the visible light region play a crucial role in enabling the miniaturization of pixels required for high-definition image output from smartphones and digital cameras.

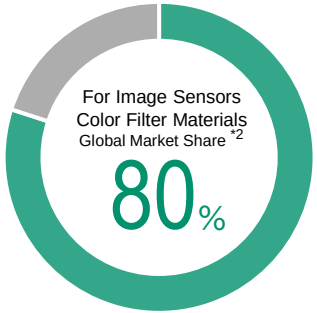
Role of Wave Control Mosaic (WCM)

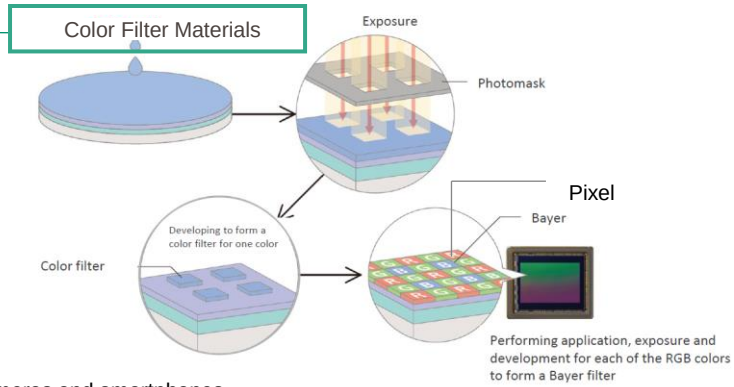
Collective term for our functional materials that control light across a broad spectrum from visible to invisible wavelengths

Visible Light	Invisible Light
Image sensors used in cameras, smartphones, etc.	Biometric authentication, security, autonomous driving

Role of color filter material for image sensors

A coloring photosensitive material used to form the color filter, a core component of the image sensor, in WCMs that detect the visible light spectrum





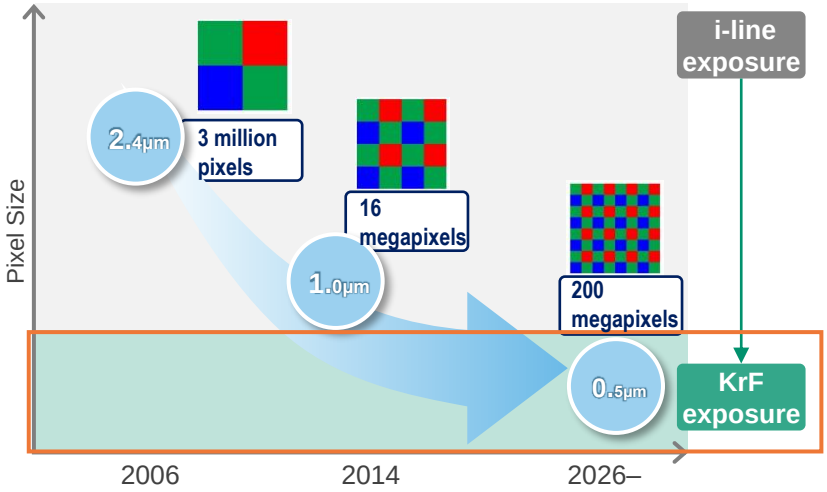
*1 A component that converts light into electrical signals in imaging devices such as cameras and smartphones

*2 Company estimate

Launched the world's first KrF exposure-compatible color filter material enabling finer pixel formation, contributing to image sensor miniaturization, higher sensitivity, and PFAS-free solutions

Customer Challenge: Desire to form ultra-fine pixels

Proposing KrF exposure. Applying functional molecular technology and organic synthesis technology cultivated through silver halide photography R&D to achieve both miniaturization and high sensitivity.



Challenge 1: Development of Color Filter Materials compatible with KrF exposure

→ **Miniaturization**

Designed and synthesized proprietary additives compatible with KrF exposure

Challenge 2 : Sensitivity reduction due to decreased light intake caused by pixel miniaturization

→ **Increased sensitivity**

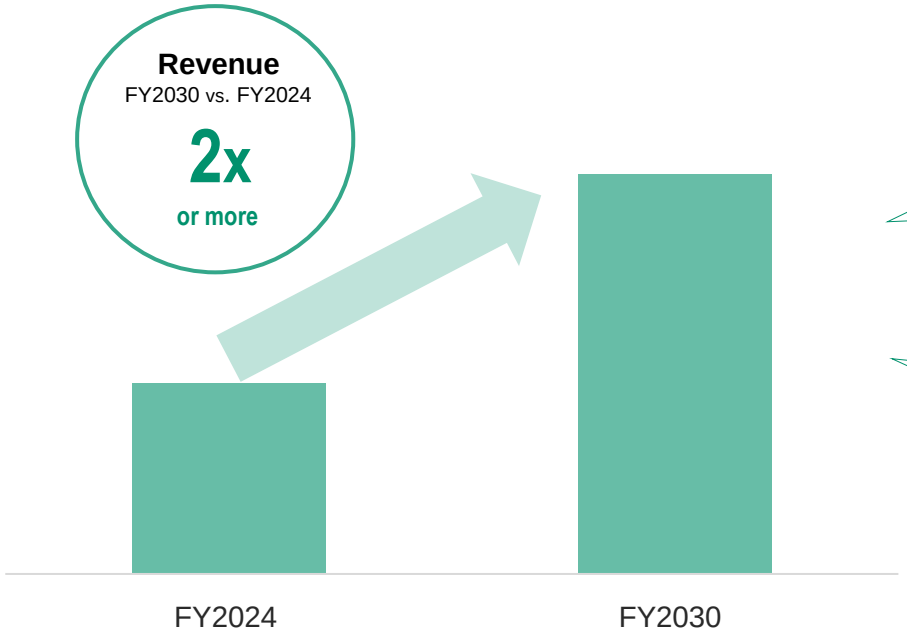
Through proprietary formulation technology, improved dye properties susceptible to heat and light, achieving both enhanced heat and light resistance and increased light absorption efficiency

Challenge 3: Environmental adaptation

→**PFAS-free**

Collaborated with raw material suppliers to achieve PFAS-freeformulation

In addition to expanding the market in the visible light spectrum where we hold an 80% market share, we aim to more than double revenue 2030 by creating new markets through expanding our lineup of materials for image sensors



Capturing market growth driven by sensor enlargement and multi-lens cameras

Expansion to Advanced Driver Assistance Systems (ADAS) , Robotics, AR/VR, etc.

＊1 Advanced Driver Assistance Systems *2 Augmented Reality *3 Virtual Reality

FUJIFILM

Agenda

1. Overview of the semiconductor market
2. Business strategy: One-Stop Solutions
3. R&D capacity for supporting One-Stop Solutions
4. Individual materials strategy and its progress toward achieving VISION2030
5. Conclusion

Conclusion

Strengthening our One-Stop Solutions through enhanced performance of individual products

Aiming to achieve ¥500.0 billion in revenue by FY2030

1

Offering One-Stop Solutions to implement a thorough customer-oriented approach

- ✓ Solving customer challenges through a broad product lineup
- ✓ Contributing to stable operations through one-stop support for development, manufacturing, and quality control near the customer

2

Advancing the performance of individual products to maximize the problem-solving ability for customers

FY2030 Targets

- ✓ Photoresist : 20% market share in advanced resist
- ✓ CMP Slurry : No.1 market share
- ✓ Dielectric Layer Materials : Revenue 5 times higher than FY2024

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Value from Innovation